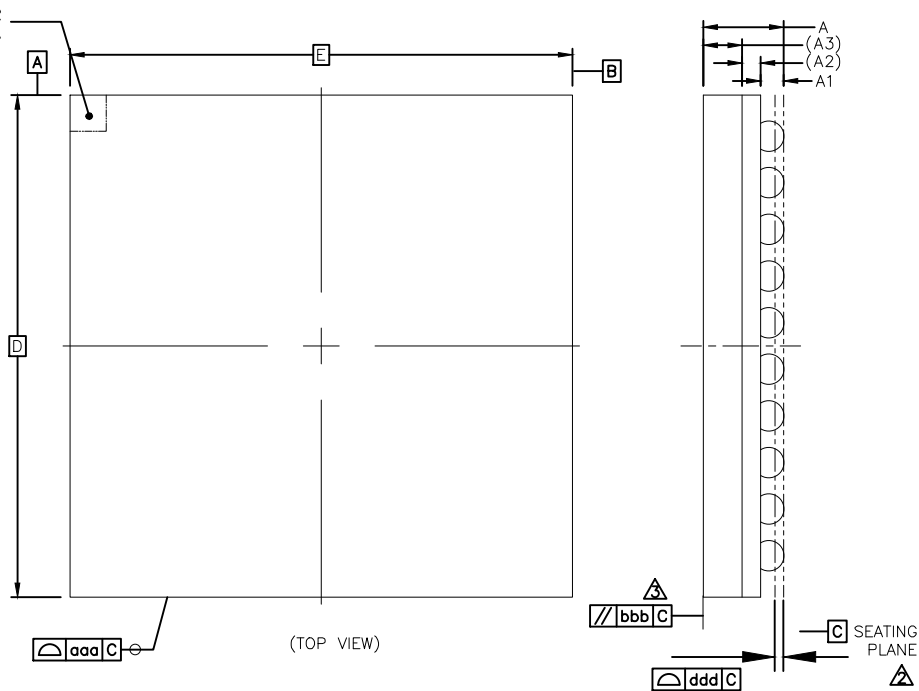
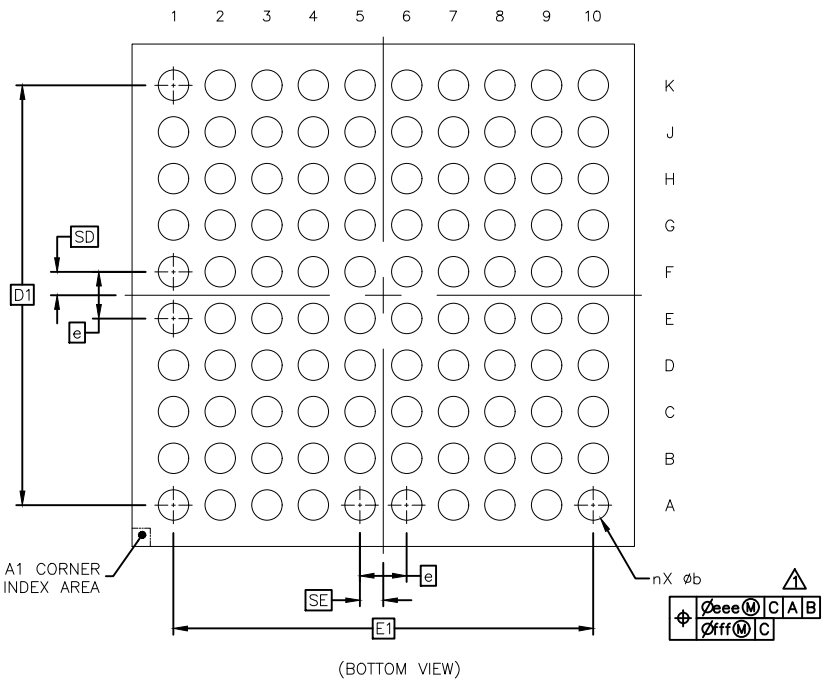


A1 CORNER INDEX AREA



(TOP VIEW)



(BOTTOM VIEW)

-DRAWING NOT TO SCALE-

	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOR.	MAX.
TOTAL THICKNESS	A	1.045	1.12	1.2
STAND OFF	A1	0.27	0.32	0.37
SUBSTRATE THICKNESS	A2	0.26		REF
MOLD THICKNESS	A3	0.54		REF
BODY SIZE	D	7		BSC
	E	7		BSC
BALL DIAMETER		0.4		
BALL OPENING		0.3		
BALL WIDTH	b	0.37	0.42	0.47
BALL PITCH	e	0.65		BSC
BALL COUNT	n	100		
EDGE BALL CENTER TO CENTER	D1	5.85		BSC
	E1	5.85		BSC
BODY CENTER TO CONTACT BALL	SD	0.325		BSC
	SE	0.325		BSC
PACKAGE EDGE TOLERANCE	aaa	0.1		
MOLD FLATNESS	bbb	0.2		
COPLANARITY	ddd	0.12		
BALL OFFSET (PACKAGE)	eee	0.15		
BALL OFFSET (BALL)	fff	0.08		

NOTES:

- ▲ DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE C.
- ▲ DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- ▲ PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- 4. PACKAGE CODE: X10077-1



TITLE:  
PACKAGE OUTLINE, 100 BALLS CTBGA  
7X7X1.12 mm

APPROVAL	DOCUMENT CONTROL NO. 21-100391	REV. A	1/1
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